



## SiC Based Miniaturized Devices, Volume II

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Deadline for manuscript  
submissions:  
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### Message from the Guest Editors

MEMS devices are found in many of today's electronic devices and systems, from airbag sensors in cars to smart phones, embedded systems, etc. Increasingly, the reduction in dimensions has led to nanometer-scale devices, called NEMS. The plethora of applications on the commercial market speaks for itself, and especially for the highly precise manufacturing of silicon-based MEMS and NEMS. While this is a tremendous achievement, silicon as a material has some drawbacks, mainly in the area of mechanical fatigue and thermal properties. Silicon carbide (SiC) is a well-known wide-bandgap semiconductor whose adoption in commercial products is experiencing exponential growth, especially in the power electronics arena. While SiC MEMS have been around for decades, in this Special Issue, we seek to capture both an overview of the devices that have been demonstrated to date, as well as bring new technologies and progress in the MEMS processing area to the forefront.





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